Surface Mount High Power Resistors

Electronics

WSMHP Series

Features:

- TO-263 surface mount package
- Very low thermal impedance to heatsink
- Non-inductive 20, 25 and 35 watt high power resistors
- Low profile package for high density PCB installation
- Suitable for board mounting with either solder or clip
- AEC-Q200 qualified



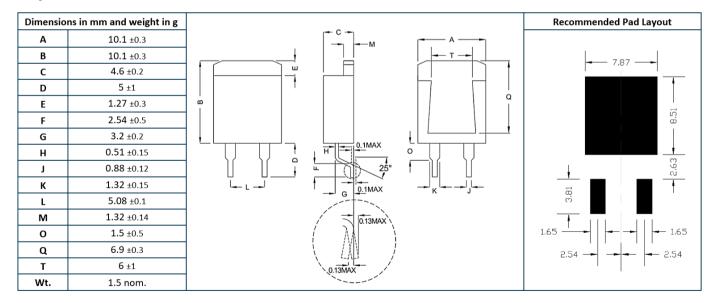


All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Electrical Data

		WSMHP20	WSMHP25	WSMHP35
Power rating on heatsink at 25°C flange temperature W		20	25	35
Power rating without heatsink	W	2.5		
Thermal resistance resistor hotspot to flange	°C/W	4.3		
Limiting element voltage	$V_{dc/acrms}$	350		
Resistance range	Ω	R50 to 100K		
Resistance tolerance	%	1, 5		
TCR 25 to 105°C	ppm/°C	1R0 to 10R: ±100, >10R: ±50		
Standard values		E24 preferred		
Insulation resistance between terminals and flange	Ω	>10G		
Dielectric strength between terminals and flange	V_{acrms}	1800		
Ambient temperature range	°C	-55 to 175		

Physical Data



Construction

A thick film resistor on an alumina substrate is mounted on a metallic flange. Leadframe is attached and the component is overmolded to form a TO-263 package.

Marking

Type, value and tolerance code are laser marked on the molded body.

Terminations

Terminations are matt tin plated copper leadframe.

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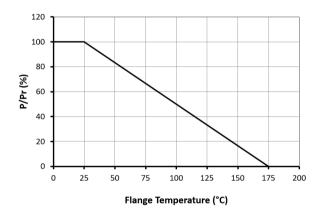


Performance Data

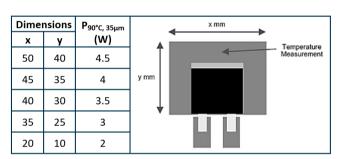
Test		Maximum
Load at rated power: 2000 hours at rated power	±ΔR%	1
Short term overload: lesser of 2 x P _r or 1.5 x LEV for 5s	±ΔR%	0.3
High temperature exposure: MIL-STD-202 method 108, 175°C for 1000 hours, no load	±ΔR%	0.25
Temperature cycling: JESD22 method JA104, -65 to +150°C, 100 cycles	±ΔR%	0.3
Biased humidity: MIL-STD-202 method 103, 85°C, 85%RH, 1000 hours, 10% of Pr	±ΔR%	0.5
Moisture resistance: MIL-STD-202 method 106, 10 cycles, 24 hours	±ΔR%	0.5
Mechanical shock: MIL-STD-202 method 213	±ΔR%	0.5
Vibration: MIL-STD-202 method 204, 20g peak, 12 cycles x 3 orientations, 10 to 2000Hz	±ΔR%	0.2
Bending strength: AEC-Q200-005, 2mm for 60s	±ΔR%	0.25
Terminal strength: AEC-Q200-006, 2.4N for 60s	±ΔR%	0.2
ESD: AEC-Q200-002, human body model, 25kV, air discharge	±ΔR%	1
Resistance to solder heat: JIS-C-5201-1 4.18, IEC 60115-1 4.18, 260 ±5°C for 10s	±ΔR%	0.5
Solderability: J-STD-002, 270 ±5°C for 3s		≥90% coverage

Thermal, Pulse & HF Data

Temperature Derating

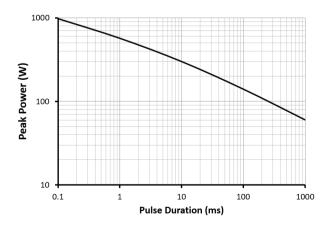


Typical Thermal Performance on FR4 Pad Heatsink



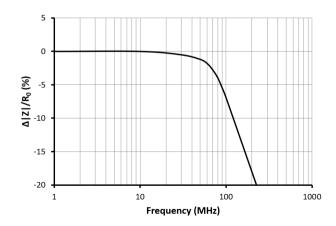
Characterisation was carried out using a 35 μ m PCB copper pad weight, with a temperature of 90°C used as a maximum reference on the PCB. P_{90°C, 35 μ m} is the power when the measurement point reaches 90°C.

Pulse Performance



Pulse performance for durations >1s depends on mounting conditions.

Typical High Frequency Performance



Typical high frequency characteristics for WSMHP35-220R. Self-resonant frequency is 1 ${\rm GHz}$.

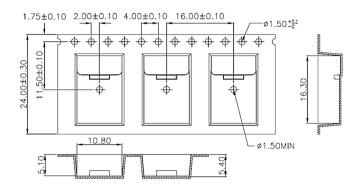
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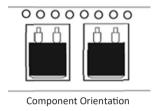




Packing

WSMHP resistors are packed on 330mm diameter reels with 99mm inner diameter, in tape of width 24mm and with a quantity of 500 pieces per reel. The dimensions of the tape and orientation of the component are as shown below.





Ordering Procedure

Example: WSMHP35-10KJ (WSMHP35, 10 kilohms ±5%, Pb-free)



1 Type	2 Value	3 Tolerance	Termination & Packing
WSMHP20	E24 = 3 / 4 characters	F = ±1%	Pb-free, tape & reel, 500/reel
WSMHP25	R = ohms	J = ±5%	
WSMHP35	K = kilohms		•

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